



Soldermask & Nomenclature Inkjet Printed

Replaces LPI (Liquid Photo Imageable) Soldermask

All Flex Solutions has been using a fully direct additive manufacturing process for applying soldermask and nomenclature since 2021. It eliminates pad contamination prior to ENIG, enhances



Rigid-Flex quality and reduces defects in an environmentally friendly, waste free process while reducing processing steps by 75%!

Soldermask printing and nomenclature marking is the next generation technology for manufacturing advanced printed circuit boards. The machine offers four-point alignment to accurately align the mask to dimensional changes, such as offset, or rotation or even for trapezoidal distortion – critical capabilities for rigid flex designs.

The machine is capable of printing nomenclature with sequential serialization, as well as bar code and QR code marking capabilities. One machine, one panel, 180 seconds to completion!

KEY INFORMATION

Fully Compliant to IPC-SM-840

Down to .004" dam or better

No mask on pads

No mask in holes

No Bare Copper contamination prior to ENIG

TAIYO IJSR-4000 JM03G (Dark Green)

Exceeds solder float test for @ 3 cycles 260C for 10 seconds

Outgassing:

TML:1.08%

CVCM:0.10%

Fully Additive Soldermask and Nomenclature Printing Process

